

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
60V	3.7mΩ@10V	110A

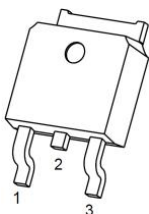
Feature

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

Applications

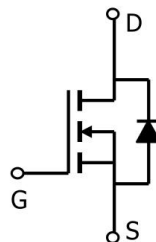
- DC-DC Converters
- Power Management

Package

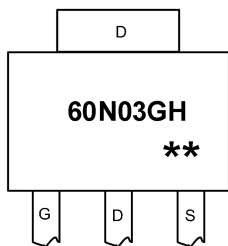


TO-252-2L(G:1 D:2 S:3)

Circuit diagram



Marking



60N03GH =Device Code
** =Week Code

**Absolute maximum ratings (Ta=25°C unless otherwise noted)**

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹ (Tc=25°C)	I_D	110	A
Pulsed Drain Current ²	I_{DM}	440	A
Single Pulse Avalanche Energy ³	E_{AS}	756	mJ
Total Power Dissipation ⁴ (Tc=25°C)	P_D	110	W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	1.13	°C/W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

Electrical characteristics (Ta=25°C, unless otherwise noted)

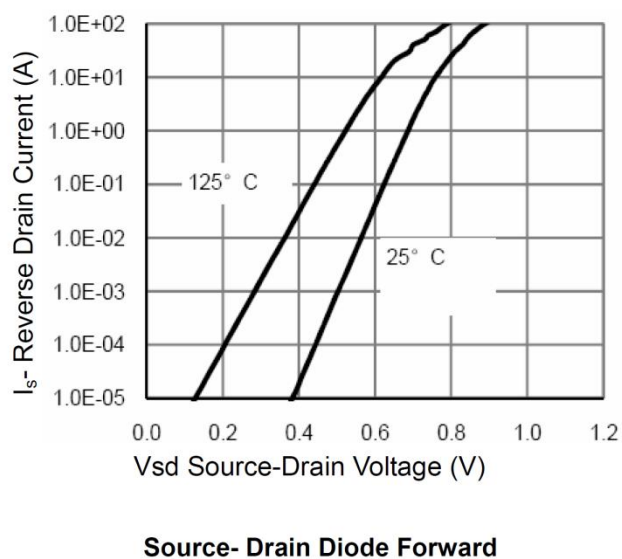
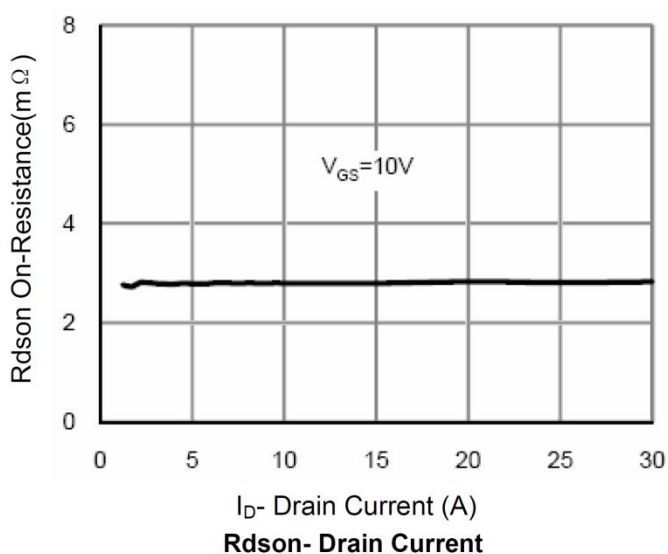
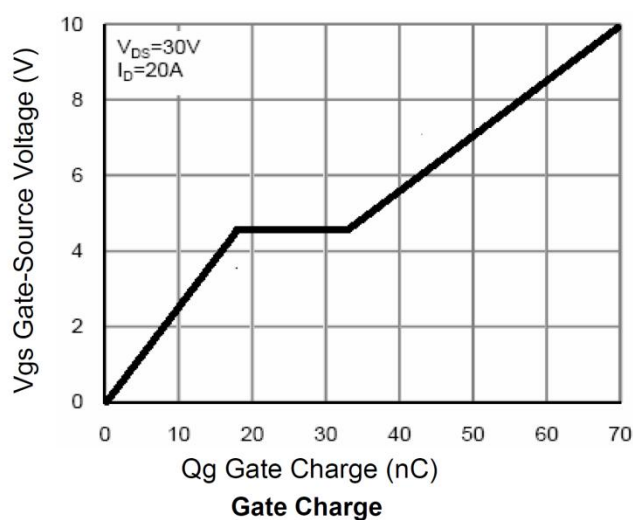
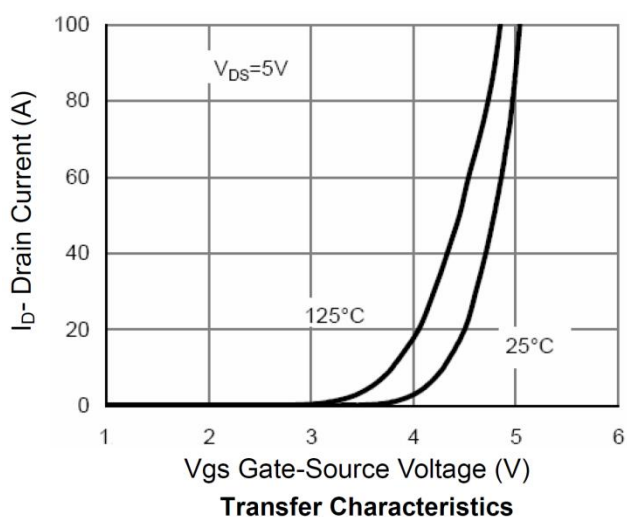
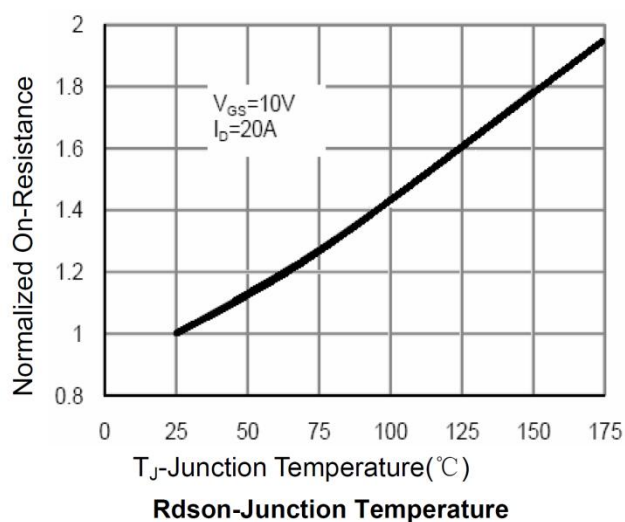
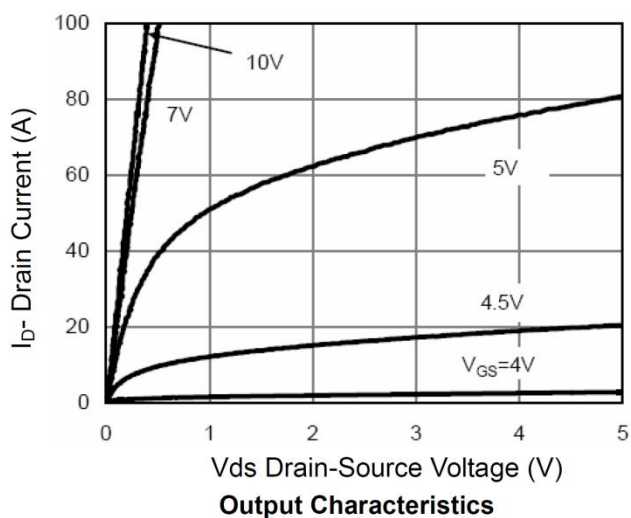
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	VGS=0V , ID=250uA	60	---	---	V
Drain-Source Leakage Current	IDSS	VDS=48V , VGS=0V	---	---	1	uA
Gate-Source Leakage Current	IGSS	VGS=±20V , VDS=0V	---	---	±100	nA
Gate Threshold Voltage	VGS(th)	VGS=VDS , ID =250uA	2.0	2.5	4.0	V
Static Drain-Source On-Resistance ²	RDS(ON)	VGS=10V , ID=20A	---	3.7	4.7	mΩ
Dynamic characteristics						
Input Capacitance	Ciss	VDS=30V , VGS=0V , f=1MHz	---	4250	---	pF
Output Capacitance	Coss		---	975	---	
Reverse Transfer Capacitance	Crss		---	41	---	
Switching Characteristics						
Total Gate Charge	Qg	VDS=30V , VGS=10V , ID=20A	---	68	---	nC
Gate-Source Charge	Qgs		---	19	---	
Gate-Drain Charge	Qgd		---	14	---	
Turn-On Delay Time	Td(on)	VDD=30V , VGS=10V , RG=4.7Ω, ID=20A	---	6	---	ns
Rise Time	Tr		---	12	---	
Turn-Off Delay Time	Td(off)		---	24	---	
Fall Time	Tf		---	5	---	
Diode Characteristics						
Diode Forward Voltage2	VSD	VGS=0V , IS=1A , TJ=25℃	---	---	1.2	V

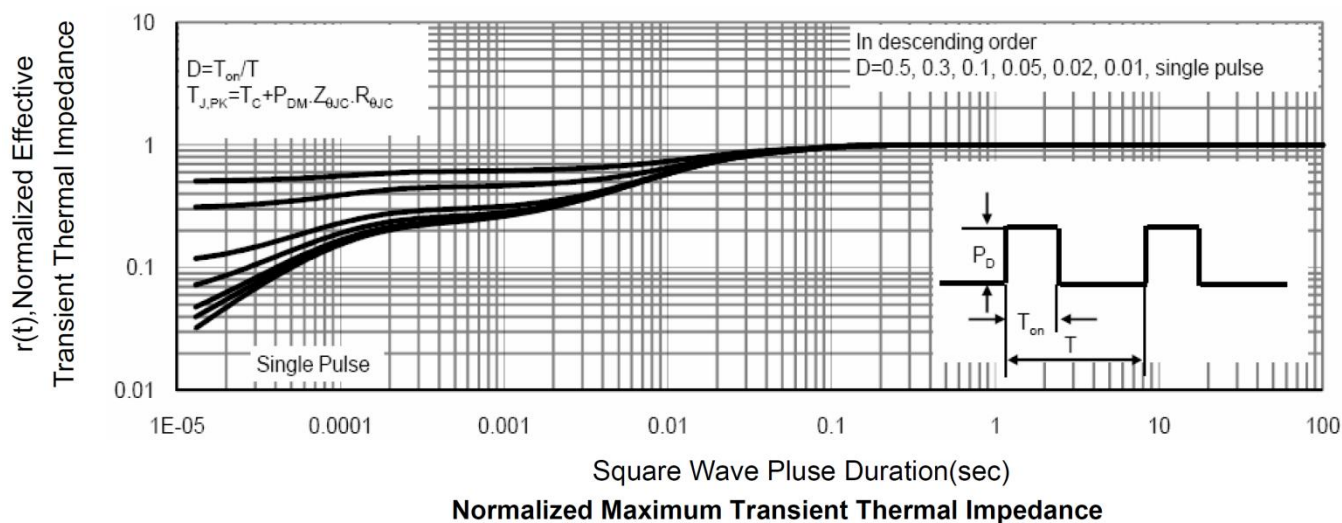
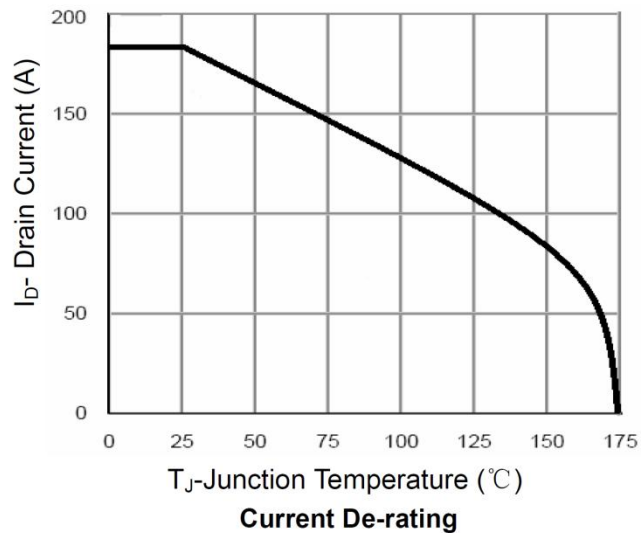
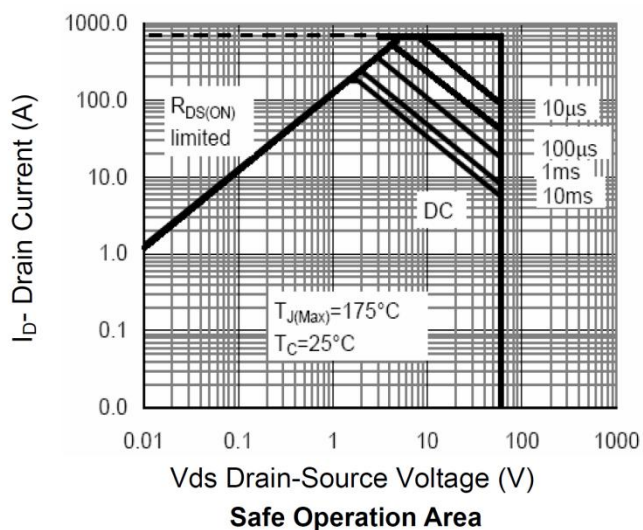
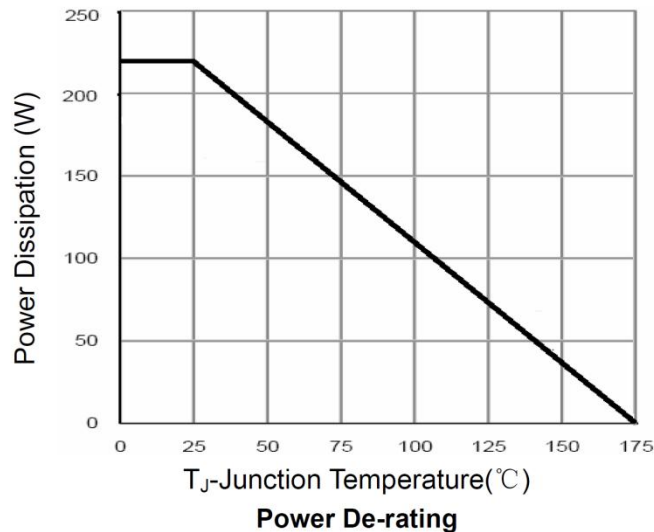
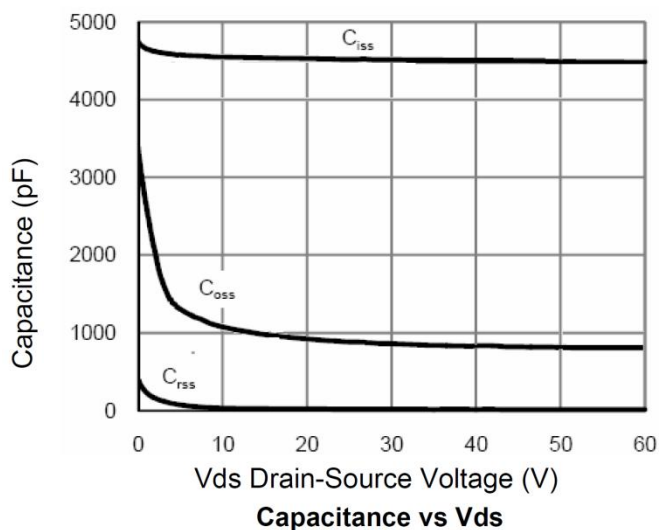
Note :

- The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- The EAS data shows Max. rating . The test condition is $V_{DD}=30V, V_{GS}=10V, L=0.5mH, R_G=25\Omega$
- The power dissipation is limited by 150°C junction temperature
- The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



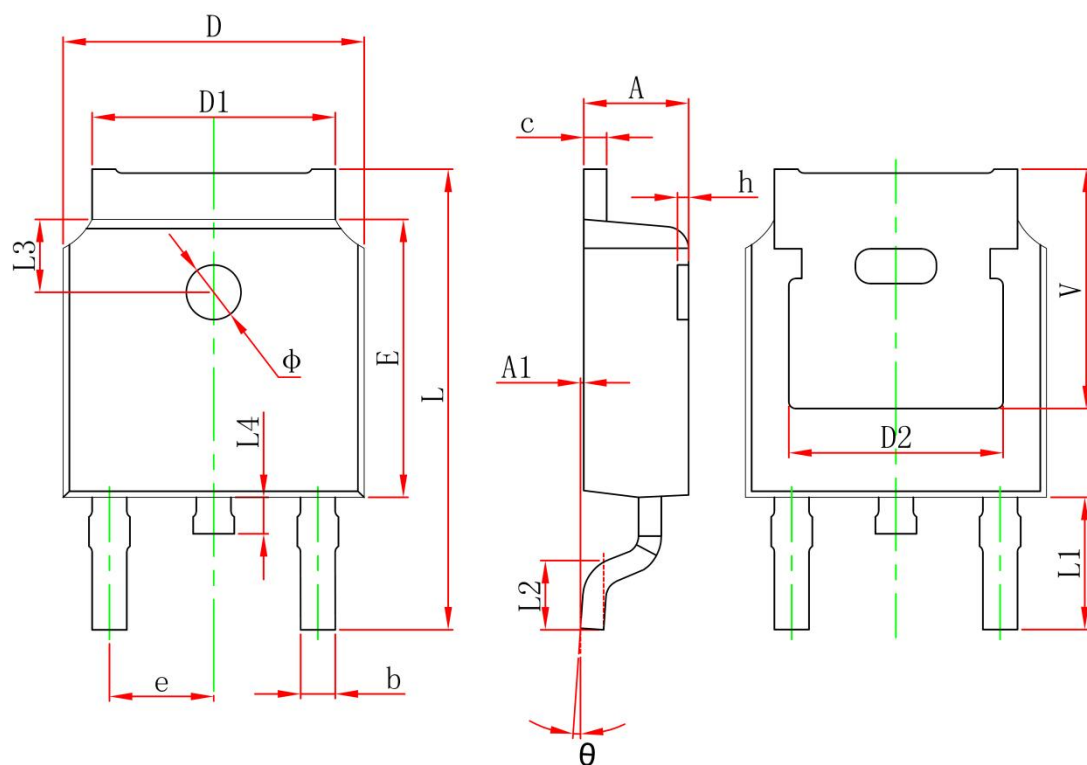
Typical Characteristics







TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
ϕ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	